

# FS50KMJ-03F

High-Speed Switching Use  
Nch Power MOS FET

REJ03G0251-0100

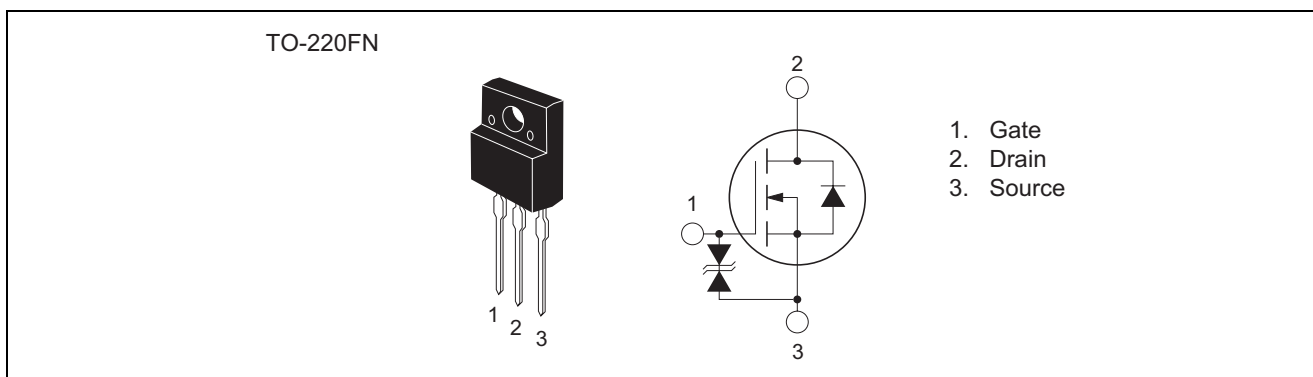
Rev.1.00

Aug.20.2004

## Features

- Drive voltage : 4 V
- $V_{DSS}$  : 30 V
- $r_{DS(ON)(max)}$  : 12.2 m $\Omega$
- $I_D$  : 50 A
- Recovery Time of the Integrated Fast Recovery Diode (TYP.) : 50 ns

## Outline



## Applications

Motor control, lamp control, solenoid control, DC-DC converters, etc.

## Maximum Ratings

( $T_c = 25^\circ\text{C}$ )

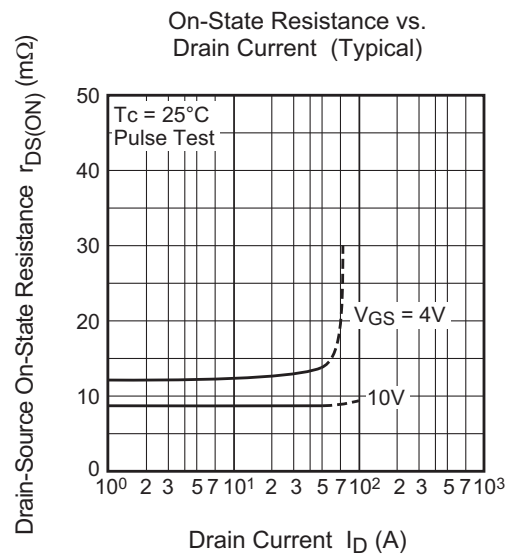
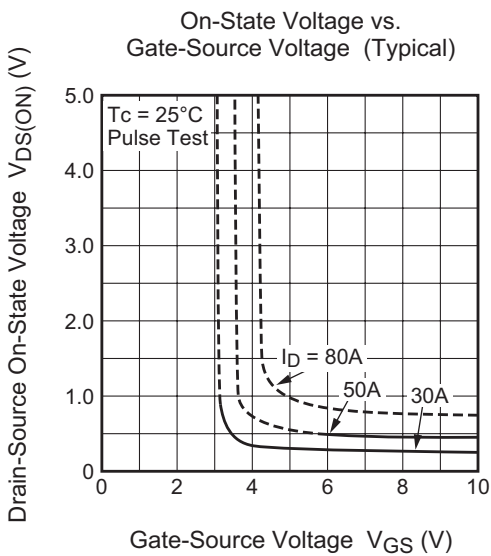
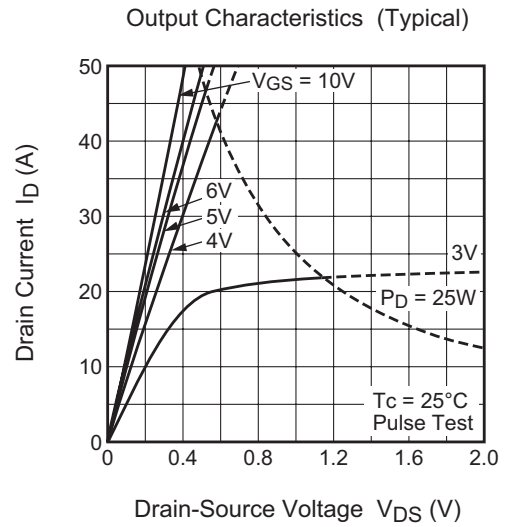
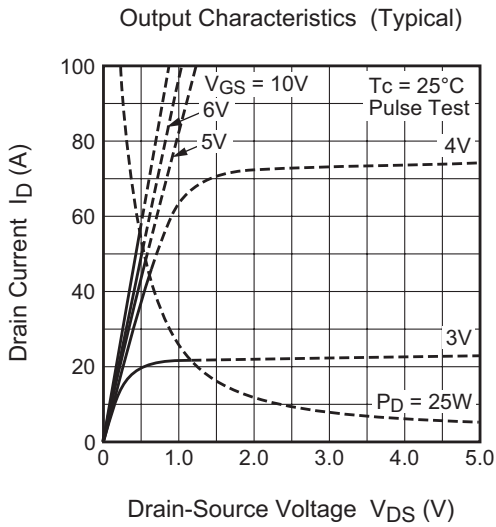
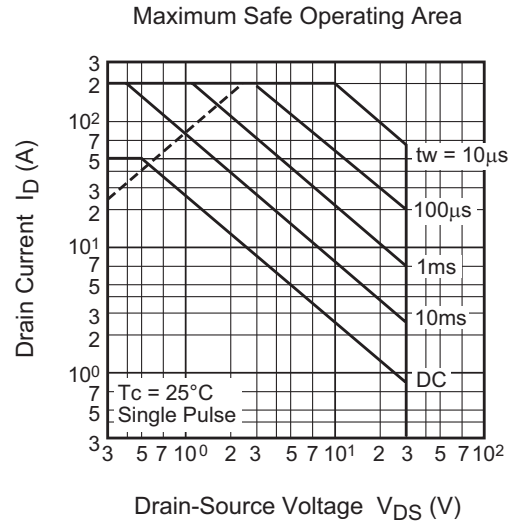
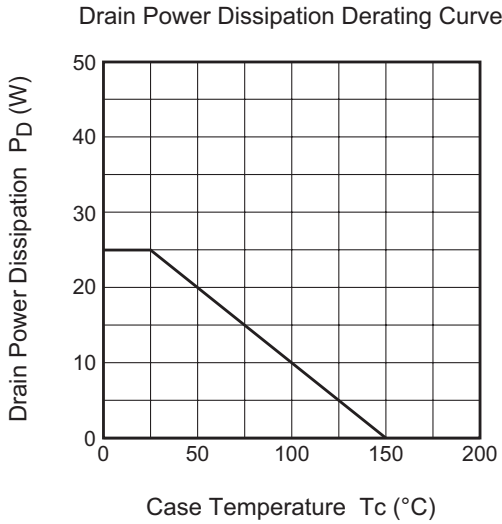
Parameter	Symbol	Ratings	Unit	Conditions
Drain-source voltage	$V_{DSS}$	30	V	$V_{GS} = 0\text{ V}$
Gate-source voltage	$V_{GSS}$	$\pm 20$	V	$V_{DS} = 0\text{ V}$
Drain current	$I_D$	50	A	
Drain current (Pulsed)	$I_{DM}$	200	A	
Avalanche current (Pulsed)	$I_{DA}$	50	A	$L = 6\ \mu\text{H}$
Source current	$I_S$	50	A	
Source current (Pulsed)	$I_{SM}$	200	A	
Maximum power dissipation	$P_D$	25	W	
Channel temperature	$T_{ch}$	- 55 to +150	$^\circ\text{C}$	
Storage temperature	$T_{stg}$	- 55 to +150	$^\circ\text{C}$	
Isolation voltage	Viso	2000	V	AC 1 minute, Terminal to case
Mass	—	2.0	g	Typical value

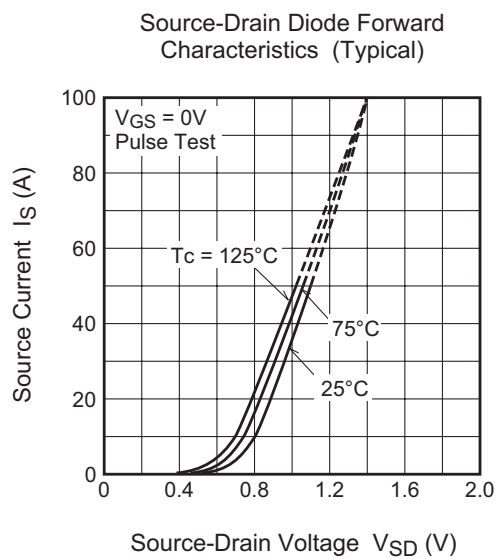
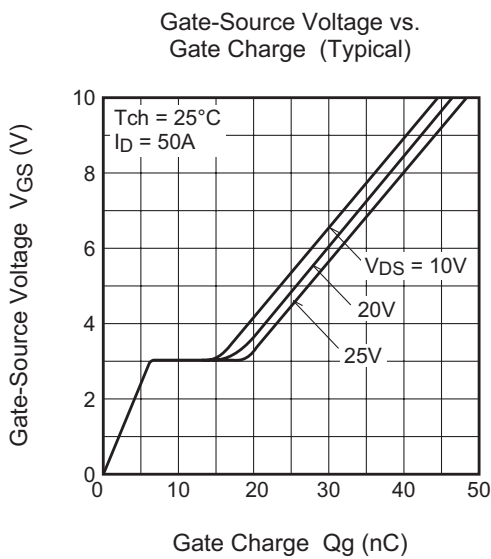
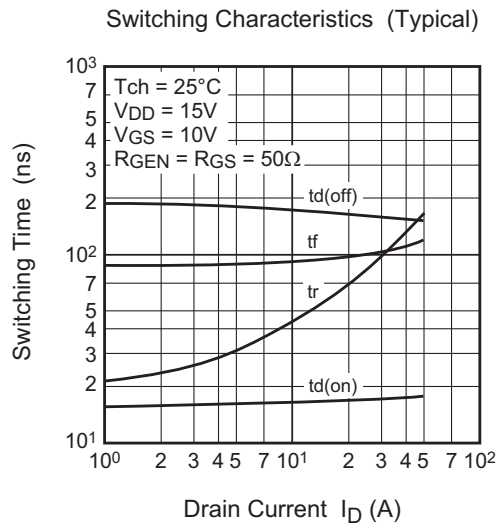
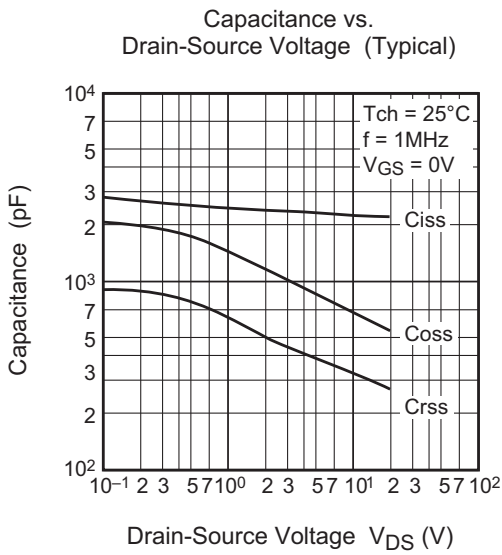
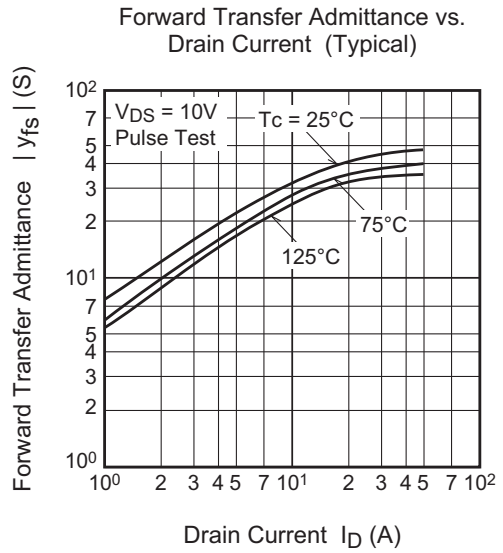
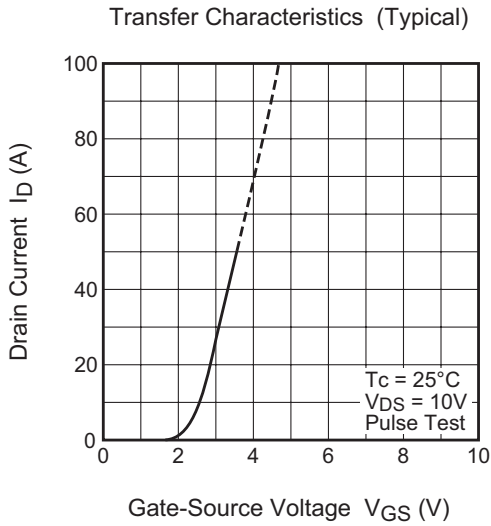
## Electrical Characteristics

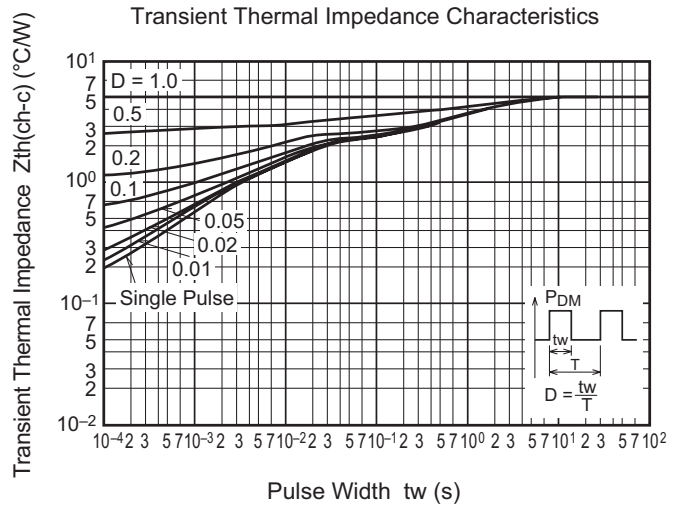
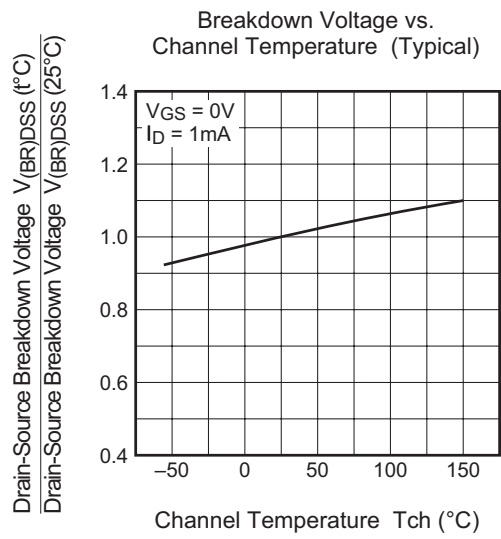
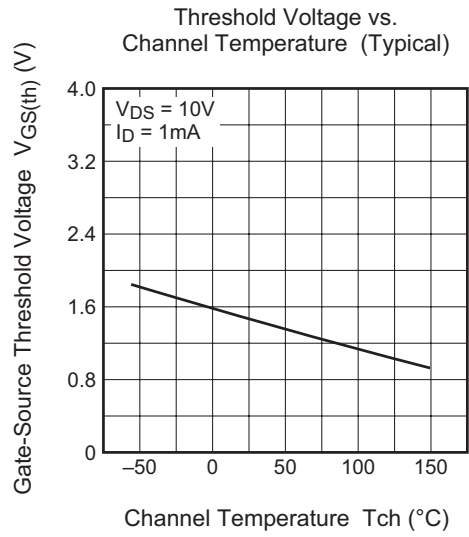
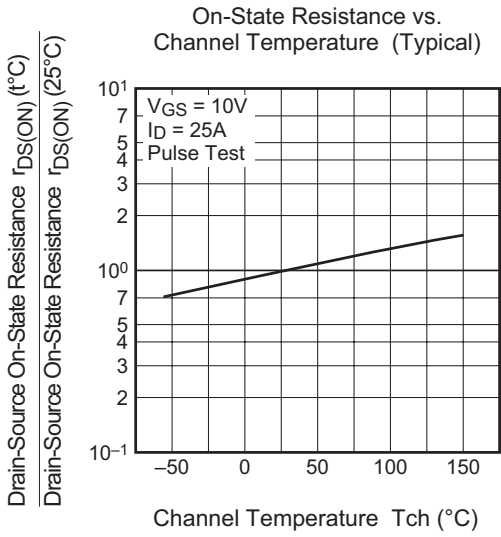
(T<sub>ch</sub> = 25°C)

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test conditions
Drain-source breakdown voltage	$V_{(BR)DSS}$	30	—	—	V	$I_D = 1 \text{ mA}$ , $V_{GS} = 0 \text{ V}$
Gate-source breakdown voltage	$V_{(BR)GSS}$	±20	—	—	V	$I_G = \pm 100 \text{ } \mu\text{A}$ , $V_{DS} = 0 \text{ V}$
Drain-source leakage current	$I_{DSS}$	—	—	100	μA	$V_{DS} = 30 \text{ V}$ , $V_{GS} = 0 \text{ V}$
Gate-source leakage current	$I_{GSS}$	—	—	±10	μA	$V_{GS} = \pm 20 \text{ V}$ , $V_{DS} = 0 \text{ V}$
Gate-source threshold voltage	$V_{GS(th)}$	1.0	1.5	2.0	V	$I_D = 1 \text{ mA}$ , $V_{DS} = 10 \text{ V}$
Drain-source on-state resistance	$r_{DS(ON)}$	—	9.2	12.2	mΩ	$I_D = 25 \text{ A}$ , $V_{GS} = 10 \text{ V}$
Drain-source on-state resistance	$r_{DS(ON)}$	—	13	19	mΩ	$I_D = 25 \text{ A}$ , $V_{GS} = 4 \text{ V}$
Drain-source on-state voltage	$V_{DS(ON)}$	—	0.23	0.31	V	$I_D = 25 \text{ A}$ , $V_{GS} = 10 \text{ V}$
Forward transfer admittance	$ y_{fs} $	—	45	—	S	$I_D = 25 \text{ A}$ , $V_{DS} = 10 \text{ V}$
Input capacitance	$C_{iss}$	—	2100	—	pF	$V_{DS} = 10 \text{ V}$ , $V_{GS} = 0 \text{ V}$ , $f = 1 \text{ MHz}$
Output capacitance	$C_{oss}$	—	690	—	pF	
Reverse transfer capacitance	$C_{rss}$	—	340	—	pF	
Turn-on delay time	$t_{d(on)}$	—	16	—	ns	$V_{DD} = 15 \text{ V}$ , $I_D = 25 \text{ A}$ , $V_{GS} = 10 \text{ V}$ , $R_{GEN} = R_{GS} = 50 \text{ } \Omega$
Rise time	$t_r$	—	90	—	ns	
Turn-off delay time	$t_{d(off)}$	—	130	—	ns	
Fall time	$t_f$	—	85	—	ns	
Source-drain voltage	$V_{SD}$	—	1.0	1.5	V	$I_S = 25 \text{ A}$ , $V_{GS} = 0 \text{ V}$
Thermal resistance	$R_{th(ch-c)}$	—	—	5.00	°C/W	Channel to case
Reverse recovery time	$t_{rr}$	—	50	—	ns	$I_S = 25 \text{ A}$ , $di/dt = -50 \text{ A}/\mu\text{s}$

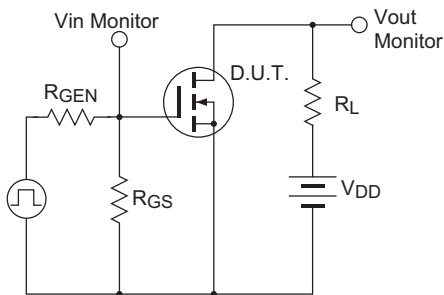
Performance Curves



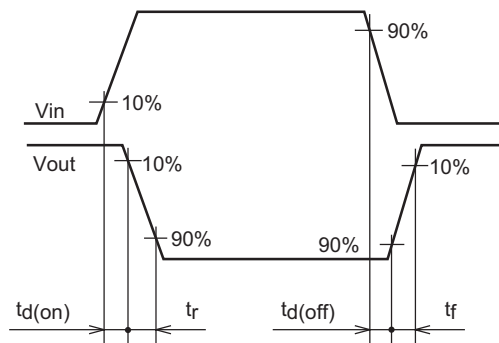




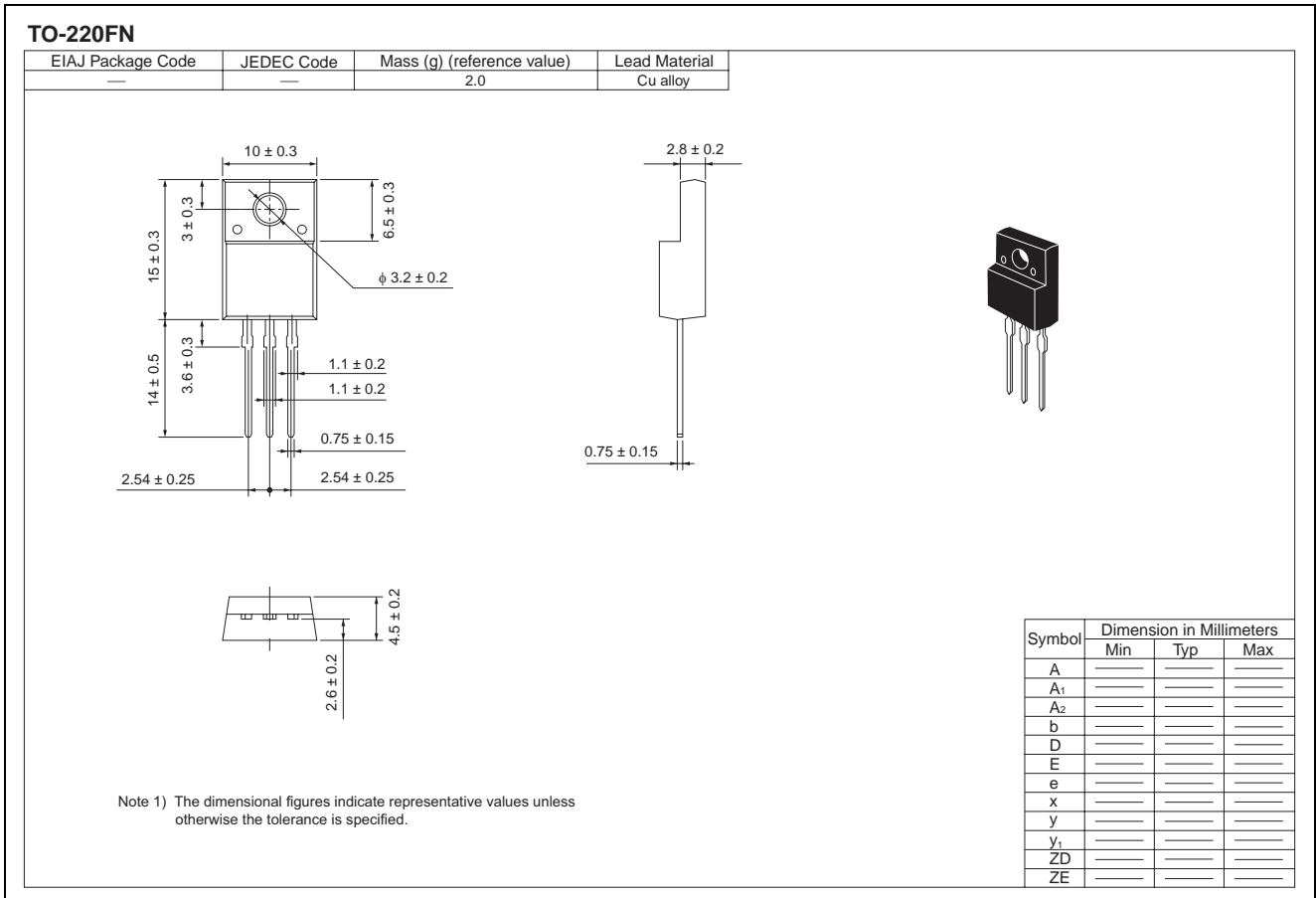
Switching Time Measurement Circuit



Switching Waveform



## Package Dimensions



## Order Code

Lead form	Standard packing	Quantity	Standard order code	Standard order code example
Straight type	Plastic Magazine (Tube)	50	Type name	FS50KMJ-03F
Lead form	Plastic Magazine (Tube)	50	Type name – Lead forming code	FS50KMJ-03F-A8

Note : Please confirm the specification about the shipping in detail.

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